

TEMPERATURE CONTROL SYSTEM FOR PLASMA PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

5 A plasma processing system that includes a temperature management system and method that can achieve very accurate temperature control over a plasma processing apparatus is disclosed. In one embodiment, the temperature management system and method operate to achieve tight temperature control over surfaces of the plasma processing apparatus which interact with the plasma during
10 fabrication of semiconductor devices. The tight temperature control offered by the invention can be implemented with combination heating and cooling blocks such that both heating and cooling can be provided from the same thermal interface.

PROVISIONAL PATENT APPLICATION